



DATE: 21 February, 2024

PCN #: 2661

PCN Title: Qualification of Additional Wafer Source and Wafer Diameter
Change for Select Discrete Automotive Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request immediately. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE**PCN-2661 REV 1**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
21 February, 2024	21 May, 2024	Discrete Automotive	Wafer Fab Material, Assembly Material	2661
TITLE				
Qualification of Additional Wafer Source and Wafer Diameter Change				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified Diodes internal wafer fabrication source (SFAB2) in Shanghai, China as additional wafer source with wafer diameter being changed from 6 inch to 8 inch for select automotive products listed below.</p> <p>In addition, Diodes Incorporated has also qualified the following changes.</p> <ul style="list-style-type: none">• Internal "Diodes Technology (Cheng Du) Company Limited" (CAT) for back metal (BM) process for all affected parts.• Wafer Top Metal Change from TiNiAg to NiAu at CAT for select products.• Assembly lead frame type and mold compound type changes at the existing assembly and test site for select products. <p>Full electrical characterization and reliability testing has been completed on the representative part numbers to ensure there is no change to product reliability, device functionality or electrical specifications in the datasheet.</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p>				
IMPACT				
No change in datasheet parameters and product performance				
PRODUCTS AFFECTED				
Table 1 – Affected part list to add SFAB2 as additional wafer source, add CAT for BM, and change wafer diameter from 6 inch to 8 inch				
Table 2 – Affected part list to add SFAB2 as additional wafer source and add CAT for BM				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				



Table 1 - Affected part list to add SFAB2 as additional wafer source, add CAT for BM and change wafer diameter from 6 inch to 8 inch					
SBR10M100P5Q-13*	SBR20M150D1Q-13	SBR2U60S1FQ-7*	SBR3U40S1FQ-7*	SBR3U60P5Q-13*	SBR40U200CTBQ-13
SBR10M100P5Q-13D*	SBR2M60S1FQ-7*	SBR3A40SAQ-13*	SBR3U60P1Q-13*	SBR3U60P5Q-13D*	SBR545SAFQ-13*
SBR20A60CTBQ-13					

Note: "*" Wafer Top Metal Change from TiNiAg to NiAu at CAT

Table 2 - Affected part list to add SFAB2 as additional wafer source and add CAT for BM					
SBR15U30SP5Q-13**	SBR1U200P1Q-7*				

Note: "*" Wafer Top Metal Change from TiNiAg to NiAu at CAT

*** Wafer Top Metal Change from TiNiAg to NiAu at CAT, and Assembly Lead Frame Type and Mold Compound Type Changes